

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10056667	FILING DATE 10/29/2001	CLASS 420	SUBCLASS 561	GAU 1742	EXAMINER Ip
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**APPLICANTS: Hwang Jennie;

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**CONTINUING DATA VERIFIED:

THIS APPLN CLAIMS BENEFIT OF 60/244,506 10/31/2000

AND CLAIMS BENEFIT OF 60/243,796 10/27/2000 *

(*)Data provided by applicant is not consistent with PTO records.

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no

ATTORNEY DOCKET NO

Verified and Acknowledged Examiners's initials

RJM 2 0062

TITLE : Lead-free solder compositions

U.S. DEPT. OF COMM /PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

CLAIMS ALLOWED

Assistant Examiner

Total Claims

Print Claim for
O.G.

ISSUE FEE

Amount Due Date Paid

DRAWING

Sheets Drwg. Figs. Drwg. Print Fig.

Primary Examiner

PREPARED FOR ISSUE

Application Examiner

☐ TERMINAL
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